

**Remarks/Arguments**

Applicant thanks Examiner Le for the careful examination of this application and the care explanation of the claim rejections. In response, applicant cancels claims 7, 12, 17, 21-27 and amends claims 1-6, 11, 13-16, 18-20. Applicant respectfully submits that the pending claims now distinguish over the cited references and stand patentable:

1. Claim 1, as amended, describes a interconnect structure that requires a conductive contact pad that has an inner portion over a compliant layer and an outer portion surrounding the inner portion; and that the inner portion being thinner than the outer portion. The Lutz patent does not disclose such a interconnect structure.

The Lutz patent discloses a semiconductor device with compliant electrical terminals but one can clearly see from the drawings and the specification that the Lutz patent does not disclose a contact pad that has an inner portion over a compliant layer and an outer portion thicker than the inner portion. The Office action recognizes the element 240 in Fig. 2E as the inner portion of a contact 200 and the element 220 as the compliant layer. Fig. 2E, or any other drawing figure, however, does not disclose an outer portion of this contact pad 200 that is thicker than the inner portion 240. In fact, the element 240 is consistently the thickest portion of the terminal structure.

Because the Lutz patent fails to disclose the interconnect structure described in claim 1, it does not anticipate claim 1 and claim 1 stands patentable over the Lutz patent.

2. Claims 2-6 and 8-11 depend from claim 1, and they therefore stand patentable at least for the same reason presented above.

3. Claim 13 also requires a contact pad that has an inner portion over a compliant layer and an outer portion surrounding the inner portion; and that the inner portion being thinner than the outer portion. For the same reason set forth with claim 1, the Lutz patent does not anticipate claim 13 and claim 13 stands patentable over the Lutz patent.

4. Claims 14-16 and 18-20 depend from claim 13, and they therefore stand patentable at least for the same reason as with claim 13.

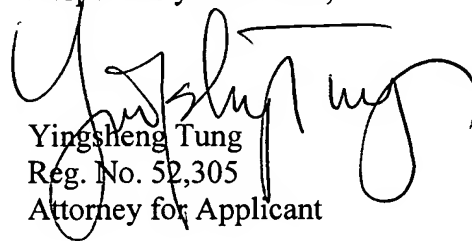
Appl. No. 10/750,059  
Amdt. dated May 16, 2005  
Reply to Office action of feb. 15, 2005

5. The other references cited in the Office action also fail to disclose the limitation set forth above. Therefore, none of the claims would be rendered obvious in view of those references.

In conclusion, applicant respectfully submits that this application is in allowable form and all pending claims distinguish over the cited references in the Office action. Applicant respectfully requests further examination of this application and timely allowance of the pending claims.

Texas Instruments Incorporated  
P. O. Box 655474 MS 3999  
Dallas, TX 75264  
(972) 917-5355

Respectfully submitted,



Yingsheng Tung  
Reg. No. 52,305  
Attorney for Applicant